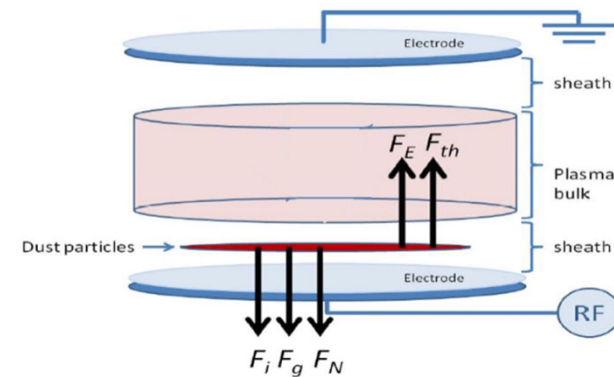


Curtis M., Simran S., Samuel Y., Michael W., Muhammad T. and Charleston C.

- Gas phase nucleation & plasma etching
 - Contamination particles “dusty”
- Impacts overall yield and equipment efficiency
 - Size (nm) defects in downstream processes
- Process & species in the process, gas, or substrate
 - Electrostatics, transport, and clustering
 - Flow rate, temperature, and pressure control
 - Sheath, plasma boundary (“-” charge particle)



Beckers, J. (2011). Dust Particle(s) (as) Diagnostics in Plasmas. Phd thesis. Eindhoven University of Technologie. 1-36.

- Formation of -'ve ion cluster (example, Silane)
 - $e + \text{SiH}_4 \rightarrow \text{SiH}_3^- + \text{H}$
 - $\text{Si}_j\text{H}_x^- + \text{SiH}_y \rightarrow \text{Si}_{j+1}\text{H}_z^- + (\text{H products})$
- Addition of -'ve dust particles complicate the equilibrium plasma structure in a discharge:
 - Particles induce e^- loss ($n_e \ll n_{\text{dust}}, n_i$) and lead to electronegative plasma equilibrium w/ higher T_e

- Introduce electrostatic particle traps
 - Create grooves (μm to mm) into electrode
 - Adjust gas flow rate (≈ 200 sccm)
- Apply bias voltage (≥ 425 V) to the substrate
- Mount substrate vertically
- Pulsed Power Modulation
- Use laser beam
- Use high gas flow